



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T2535-600G	7BD1*246SBC1	A	SHENZHEN B/E	2016-05-04
Amount		UoM	Unit type	ST ECOPACK Grade
1380.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	GULL WING	
Comment	D2PAK CLIP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7BD1*2465BC1									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	15.288	mg	supplier	die	Silicon (Si)	7440-21-3		13.252	mg	866824	9603				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.266	mg	17399	193				
				supplier	metallization	Gold (Au)	7440-57-5		0.050	mg	3270	36				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.075	mg	4906	54				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.017	mg	1112	12				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.360	mg	23548	261				
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.107	mg	6999	77				
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	1.161	mg	75942	841				
				Leadframe	Copper & its alloys	900.740	mg	supplier	alloy	Copper (Cu)	7440-50-8		899.839	mg	999000	652057
								supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.901	mg	1000	653
Soft solder	Solder	13.977	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	12.929	mg	925020	9369				
				supplier	solder	Silver (Ag)	7440-22-4		0.699	mg	50010	507				
				supplier	solder	Tin (Sn)	7440-31-5		0.349	mg	24970	253				
Encapsulation	Other Organic Materials	412.056	mg	supplier	mold compound	Silica, vitreous	60676-86-0		313.163	mg	760001	226930				
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		42.030	mg	102001	30457				
				supplier	mold compound	Phenol resin	9003-35-4		24.723	mg	59999	17915				
				supplier	mold compound	Others	Proprietary		20.603	mg	50000	14930				
				supplier	mold compound	Metal hydroxide	21645-51-2		8.241	mg	20000	5972				
				supplier	mold compound	Carbon black	1333-86-4		3.296	mg	7999	2388				
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575				
Clip	Copper & its alloys	31.625	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	22917				